



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

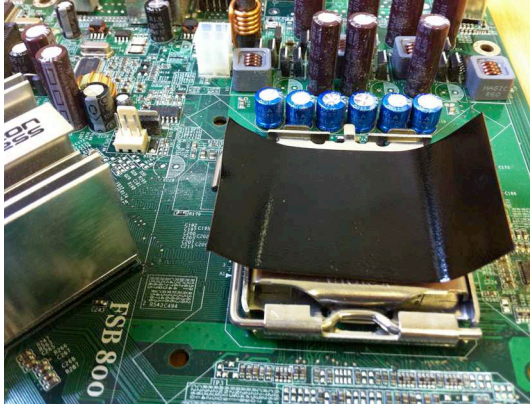
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# PH3n High Performance Heat Spreader



## Features

- Gives a typical junction temperature reduction of 20°C
- Gives design flexibility
- Die cut for custom shapes

## Applications

- Electronic components: IC / CPU / MOS
- LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....
- DDR II Module / DVD Applications / Hand-Set applications etc...

## Properties

- REACH Compliant
- RoHS Compliant

Property	PH3n			Test Method	Unit
Colour	Black	Black	Black	Visual	-
Thickness	0.062	0.07	0.1	-	mm
Metal layer	CU foil	CU foil	CU foil	-	-
PET layer thickness	0.025	0.025	0.025	ADTM D374	mm
Coating layer thickness	0.025	0.025	0.025	-	mm
Metal layer thickness	0.012	0.02	0.02	-	mm
Filler	Nano tube	Nano tube	Nano tube	-	-
Application temperature	-30 to 120	-30 to 120	-30 to 120	-	°C
Short time temp. @ 30sec	200	200	200	-	°C
Low molecular weight Siloxane content	0	0	0	-	ppm
Heat emissivity coefficient	0.96	0.96	0.96	ADTM D149	1
Dielectric strength (AV)	>2	>2	>2	ADTM D149	kV
Metal layer thermal conductivity	400	400	400	ADTM D5470	W/mk
Coated layer thermal conductivity	1.2	1.2	1.2	ADTM D5470	W/mk

Available with an adhesive backing

